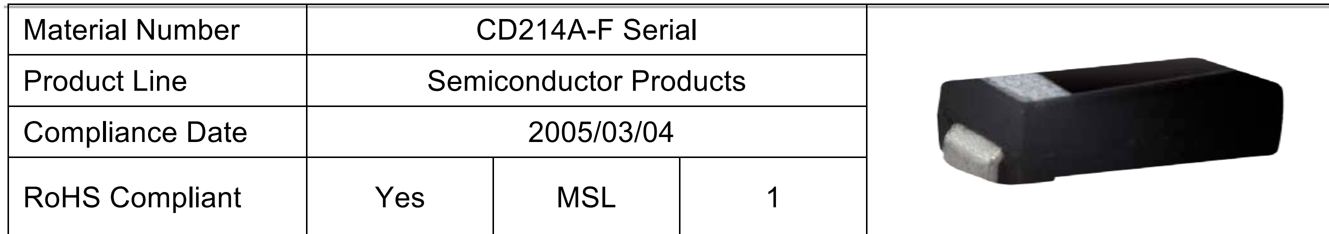
MATERIAL DECLARATION SHEET



Material Number	CD214A-F Serial		
Product Line	Semiconductor Products		
Compliance Date	2005/03/04		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Solder wafer	Metal	1.72	Lead *3	7439-92-1	92.5	2.49	2.69
				Tin	7440-31-5	5	0.13	
				Silver	7440-22-4	2.5	0.07	
2	Dice	Metal	2.37	Silicon	7440-21-3	73.54	2.720	3.7
				Nickel	7440-02-0	1.99	0.074	
				Aluminum	7429-90-5	0.56	0.021	
				Lead*4	7439-92-1	14.80	0.548	
				Phosphorus	7723-14-0	0.249	0.009	
				Boron	7440-42-8	0.874	0.032	
				Other trace metals	-	7.987	0.296	
3	Molding compound	Plastic	38.83	Silica	14808-60-7	70	42.47	60.67
				Epoxy Resin	29690-82-2	20	12.13	
				Phenol Resin	9003-35-4	8	4.85	
				Antimony trioxide	1309-64-4	2	1.21	
4	Lead Wire	Metal	20.98	Copper	7440-50-8	>99.0	32.45	32.78
				Misc not to declare	-	<1.0	0.33	
5	Plating	Metal	0.1	Tin	7440-31-5	>99.0	0.16	0.16
				Misc not to declare	-	<1.0	0.002	
		Total weight	64.0					

This Document was updated on: 2015/11/03

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

2. *：Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)；

3. *：Excepted for RoHS 7(c) I-Electrical and electronic components containing lead in a glass or ceramic other then dielectric ceramic in capacitors,e.g.piezoelectronic devices, or in a glass or ceramic matrix compound；

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